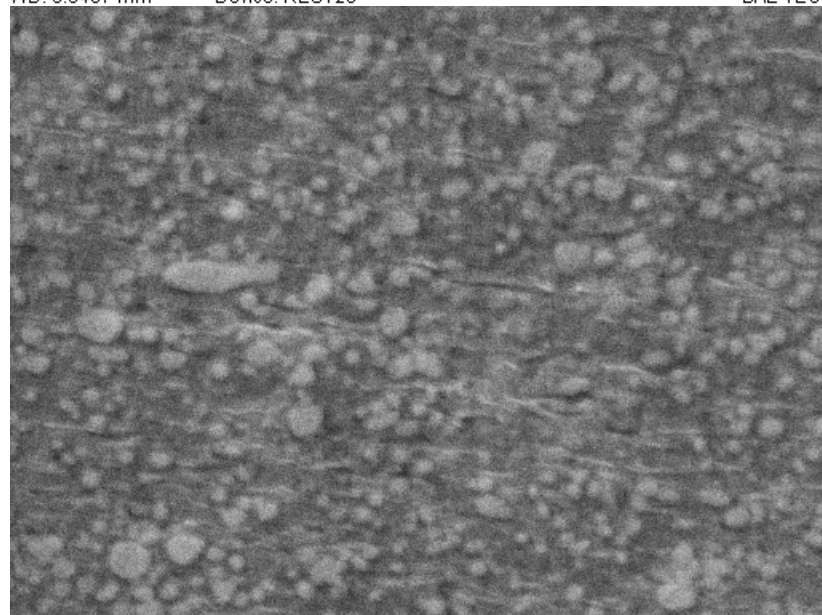
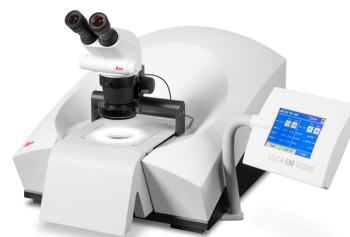




SEM MAG: 892 x DET: SE 100 um Vega@Tescan
HV: 5.0 kV DATE: 05/14/08 BAL-TEC
WD: 5.5487 mm Device: RES120



SEM MAG: 5.97 kx DET: SE 10 um Vega@Tescan
HV: 5.0 kV DATE: 05/14/08 BAL-TEC
WD: 5.4836 mm Device: RES120



Leica EM TIC020 –

Thin Plastic Film

**Market: Plastic Industry, Research Institutes,
Universities**

Companies (e.g.): 3 M, SPI, Kentucky etc.

Living up to Life

Leica

MICROSYSTEMS

Leica EM TIC020 Application No. 4/2

Thin Plastic Film

Goal:

- Cross section of thin plastic film

Process description (benchmark values for this particular sample):

Mechanical pre-preparation: Embedding in two Si pieces

Parameter	
Acceleration voltage	7 kV
Gun current	2.6mA
Milling time	4.5 h
Cut depth	600 µm
Complete process time	5 h

Results:

- Perfect cross section of the plastic film
- The film structure is clearly visible

Wolfgang Grünewald, Leica Microsystems

Wolfgang.Gruenewald@leica-microsystems.com